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**APR 20 2007**

**INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND  
METHOD OF MANUFACTURING THE SAME**

Appl. No. : 10/755,042 Confirmation No. 8665  
Applicant : Jin-Yuan Lee,  
Mou-Shiung Lin,  
Ching-Cheng Huang  
Filed : January 9, 2004  
TC/A.U. : 2815  
Examiner : Fenty, Jesse A  
Docket No. : MEGP0004USA1  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**RESPONSE TO FINAL OFFICE ACTION AND ADVISORY OFFICE ACTION**

5 Sir:

In response to the Final Office Action mailed Jan. 4, 2007 and Advisory Office Action mailed Apr. 9, 2007, please consider the remarks as follows:

**Remarks/Arguments** begin on page 2 of this paper.